

APPLICATION NO. 09/665415

October 13, 2004

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CLMPTO

1. (Currently Amended) A semiconductor device comprising:

a semiconductor element having a primary surface and a back surface, said semiconductor element having an element electrode on the primary surface; and

a circuit board having a primary surface and a back surface, a board electrode on at least the back surface, [[and]] a predetermined opening hole formed therein and external electrodes disposed on the back surface;

wherein the primary surface of said semiconductor element is bonded to the primary surface of said circuit board by means of an adhesive layer which is greater in size than the primary surface of said semiconductor element,

said adhesive layer extends outside an outer edge of the primary surface of said semiconductor element without reaching an outer edge of the primary surface of said circuit board, said adhesive layer extending outward relative to and completely all the way around the primary surface of said semiconductor element to cover an area of the circuit board under which all the external electrodes are disposed,

said element electrode of said semiconductor element is connected to said board electrode provided on the back surface of said circuit board via said opening hole, and

said semiconductor element and said circuit board directly contact each other via the adhesive layer in order to relieve tension between said semiconductor element and said circuit board by the adhesive layer.

2. (Original) The semiconductor device as according to claim 1, wherein the surrounding regions of the side surfaces of said semiconductor element on said circuit board are sealed with resin so as to assume a flange structure.

3. (Original) The semiconductor device as according to claim 1, wherein the surrounding regions of the side surfaces and back surface of said semiconductor element are sealed with resin.

4-6. (Cancelled)

#### CLAIMS 7-11 (CANCELLED)

12. (New) A semiconductor device comprising:

a semiconductor element having a primary surface and a back surface, said semiconductor element having an element electrode on the primary surface; and

a circuit board having a primary surface and a back surface, a board electrode on at least the back surface, a predetermined opening hole formed therein and external electrodes disposed on the back surface;

an adhesive layer bonding the primary surface of said semiconductor element to the primary surface of said circuit board so that said semiconductor element and said circuit board directly contact each other via the adhesive layer,

wherein said element electrode of said semiconductor element is connected to said board electrode provided on the back surface of said circuit board via said opening hole,

said adhesive layer extends outward relative to and completely all the way around the primary surface of said semiconductor element without reaching an outer edge of the primary surface of said circuit board, and covers an area of the circuit board under which all the external electrodes are disposed.